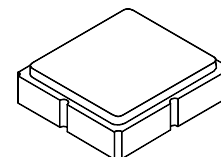


**SF2159E**

**974 MHz**  
**SAW Filter**



**SM3030-8**

- **SAW Filter for Digital Television**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

**Characteristics :**

Balance-to-balanced Operation

Terminating Source/Load Impedance :  $Z_S = 150 \Omega$

**Maximum Rating**

Rating	Value	Units
Input Power Level	0	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/ 10 seconds maximum	265	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$			974		MHz
Maximum Insertion Loss, 954 to 994 MHz	$IL_{MAX}$			3.1	4.5	dB
1.5 dB Passband				50		MHz
Amplitude Ripple, 954 to 994 MHz				1.0	2.5	dB <sub>P-P</sub>
Attenuation, Referenced to $IL_{MAX}$						
50 to 891.94 MHz			45	51		dB
1056.06 to 1100 MHz			44	55		
2000 to 6000 MHz			15	20		
Group Delay Ripple, 954 to 994 MHz				23	35	ns <sub>P-P</sub>

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	825, <u>YWWS</u>

**Electrical Connections**

	Connection	Terminals
Port 1	Balanced Input	1,2
Port 2	Balanced Output	5,6
	Ground	All Others

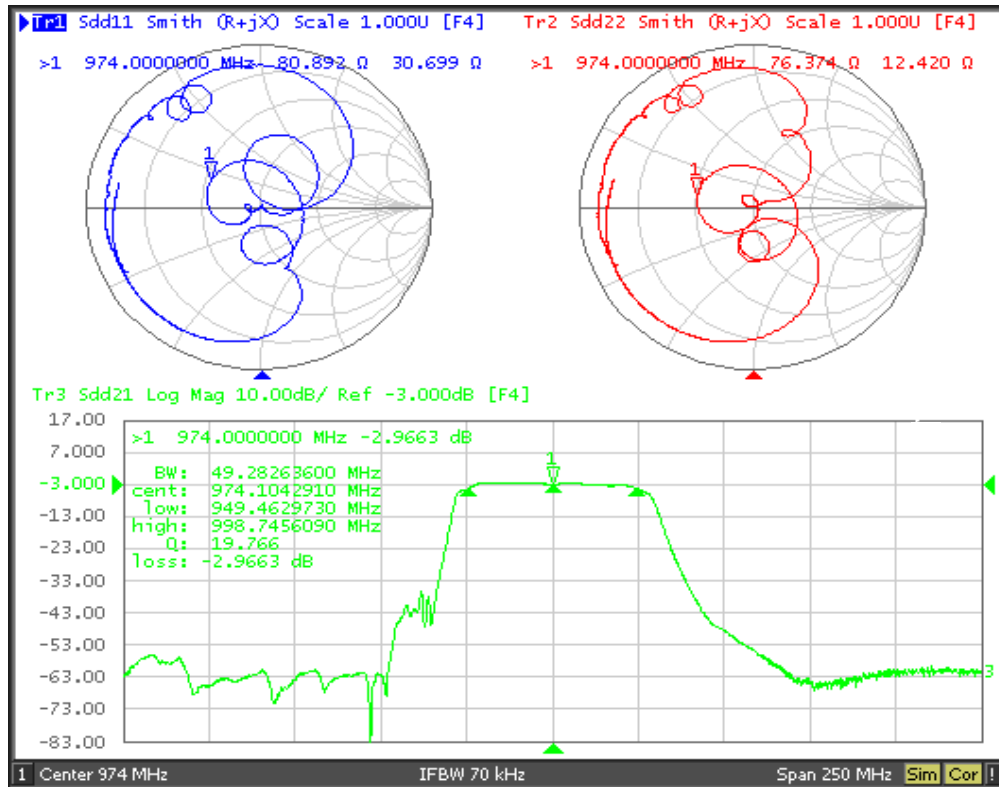
Dot Indicates Pin 1

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

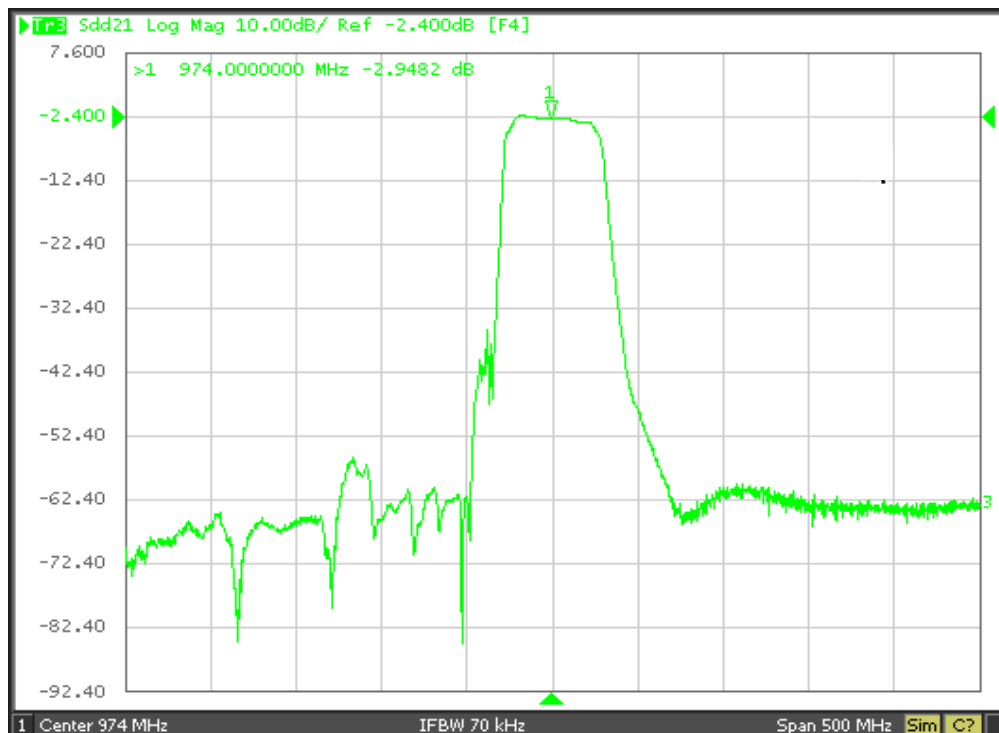
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

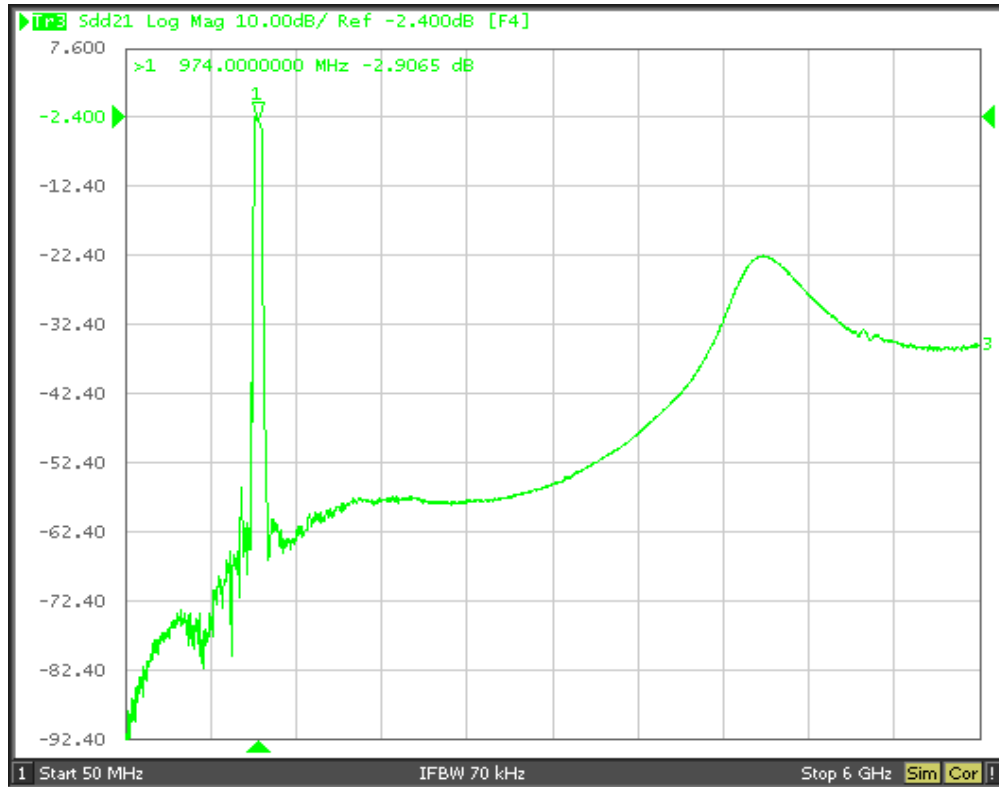
## Filter $S_{11}$ , $S_{22}$ and $S_{21}$ Plots



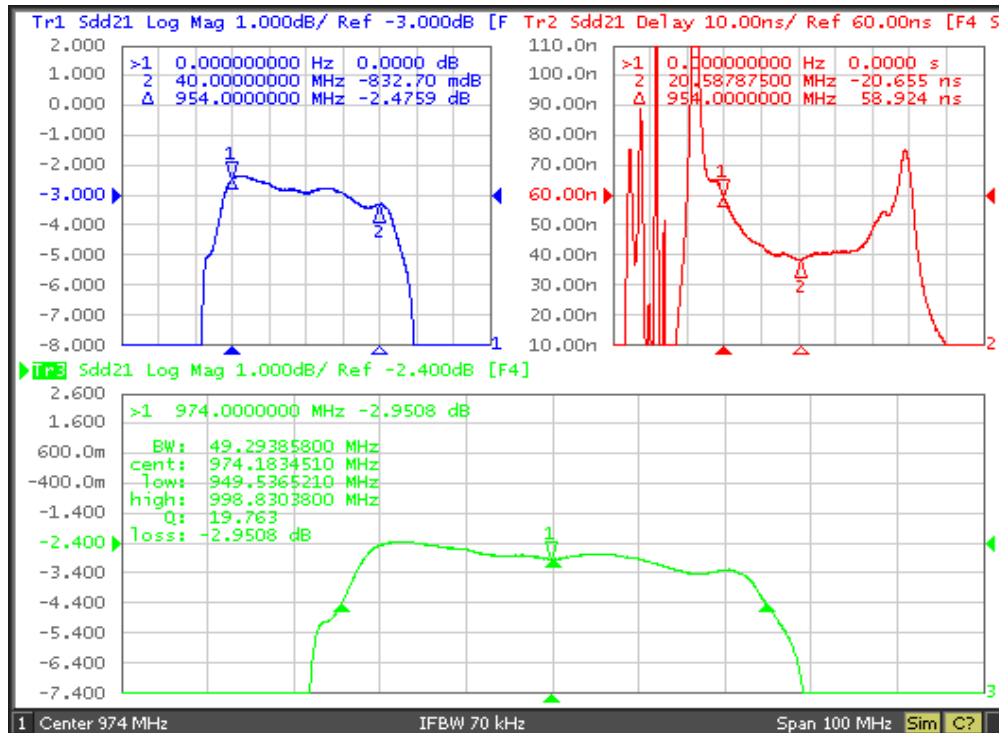
## Filter Near-in Rejection



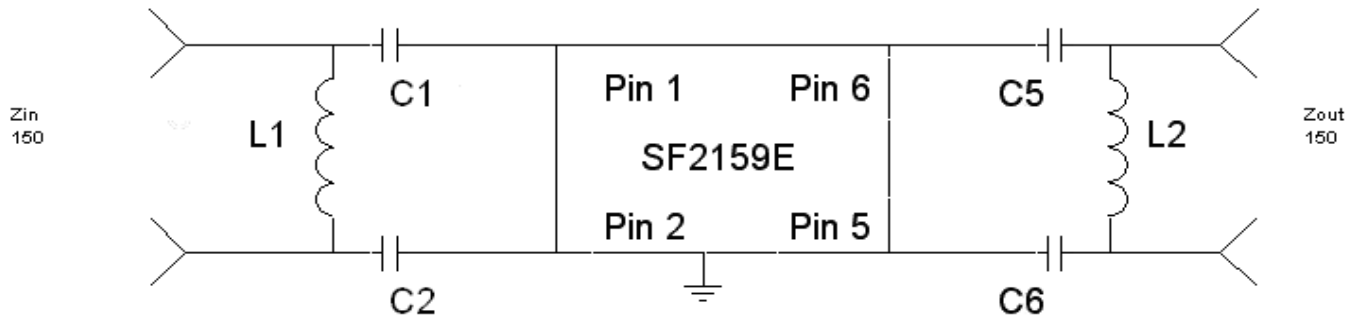
## Filter Broadband Rejection



## Filter Passband Amplitude and Group Delay Detail



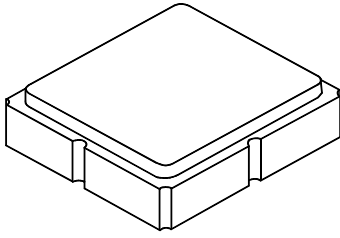
## Tuning Network, 150 ohm Balanced Source/Load



All other pins grounded

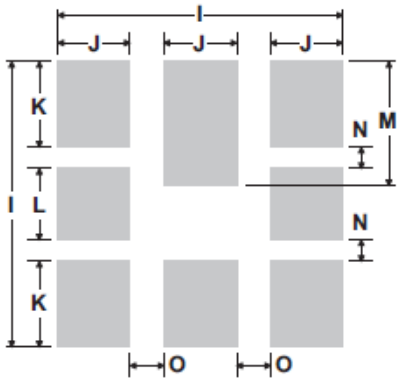
**L1, L2**      24 nH  
**C1, C2, C3, C4**    22 pF

## 8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

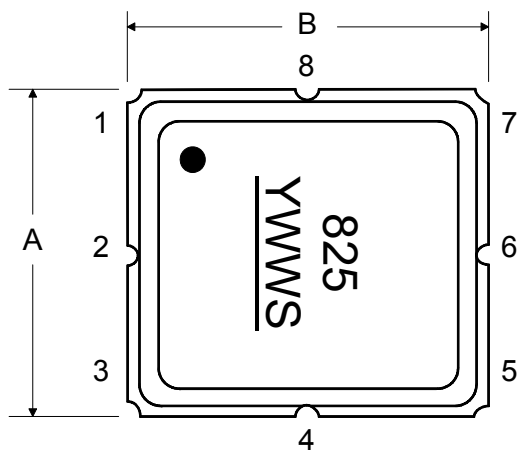


PCB Footprint Top View

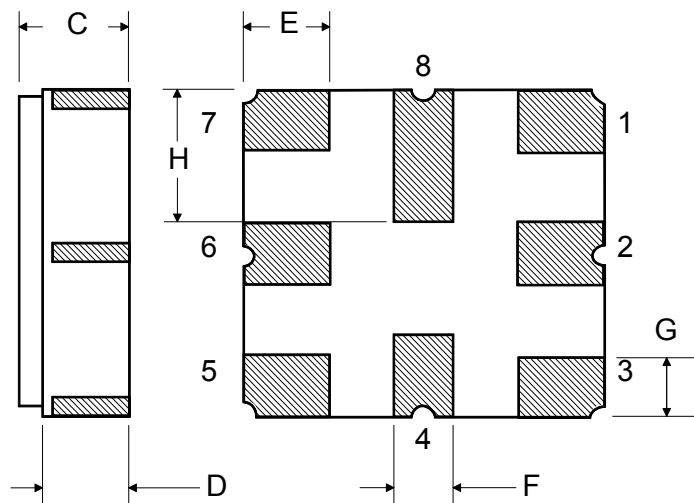
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

TOP VIEW

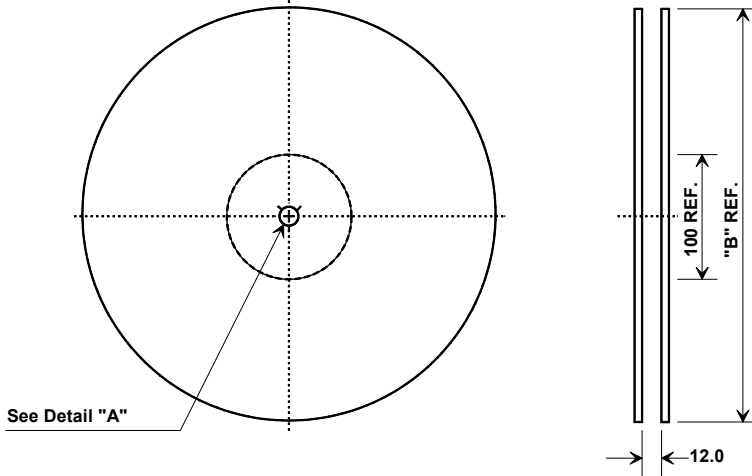


BOTTOM VIEW

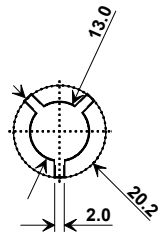


## Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.4 mm
Pitch	8.0 mm
W	12.0 mm

### COMPONENT ORIENTATION and DIMENSIONS

